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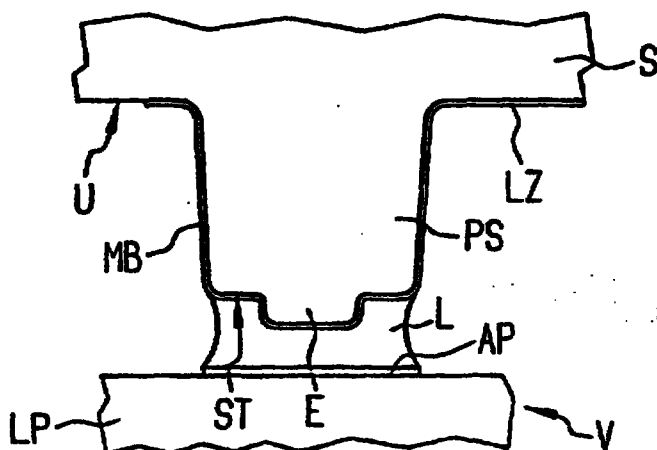
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(54) Title: SUBSTRATE WITH AT LEAST TWO METALLIZED POLYMER BUMPS FOR SOLDERED CONNECTION TO WIRING

(54) Bezeichnung: SUBSTRAT MIT MINDESTENS ZWEI METALLISIERTEN POLYMERHÖCKERN FÜR DIE LÖTVER-
BINDUNG MIT EINER VERDRAHTUNG



(57) Abstract: A substrate (S) with at least two metallized polymer bumps (PS), especially a polymer stud grid array, is configured in such a way that the polymer bumps (PS) have at least one step (ST) and at least one elevation (E). The geometry of the solder bumps (PS) ensures that the soldered connections to the wiring (V) are secure and guarantees reproducible layer thickness for the solder (L).

(57) Zusammenfassung: Ein Substrat (S) mit mindestens zwei metallisierten Polymerhöckern (PS), insbesondere ein Polymer Stud Grid Array, wird so ausgebildet, daß die Polymerhöcker (PS) mindestens eine Stufe (ST) und mindestens eine Erhöhung (E) aufweisen. Diese Geometrie der Lötbocker (PS) gewährleistet zuverlässige Lötverbindungen mit einer Verdrahtung (V) und reproduzierbaren Schichtdicken des Lots (L).

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